

Job Detail

Staff Level

Position Title	Product Marketing Manager - Global Semiconductor - Up to 15M
Recruiter Company	Michael Page International Japan K.K./マイケル・ページ・インターナショナル・ジャパン株式会社
Company Name	Company name is private
Activated / Updated	2024-05-13 / 2024-05-13
Job Type	IT (Embedded Software, Control Systems) - Project Manager
Industry	Electronics, Components, and Semiconductor Manufacturing
Location	Asia Japan Tokyo
Job Description	<p>Lead product marketing efforts for advanced Digital Lithography Technology (DLT) tools, targeting back-end packaging processes for innovative copper clad laminate (CCL) circuit boards. Collaborate with global partners, including a leading technology provider, to drive market penetration and shape the future of semiconductor packaging.</p> <p>Description</p> <ul style="list-style-type: none"> * Develop comprehensive business and marketing plans to drive competitive advantage and market share. * Conduct detailed competitive analysis for specific product lines in Advanced Packaging. * Establish pricing strategies and develop marketing tools for successful product introductions. * Collaborate with cross-functional teams to develop and enhance products, and communicate critical market needs. * Manage field support to optimize account partnerships and penetration opportunities. <p>Profile</p> <ul style="list-style-type: none"> * Possesses 5+ years of hands-on experience in semiconductor tool engineering, preferably in back-end packaging or front-end fab processes. * Demonstrates strong technical knowledge and problem-solving skills, with the ability to communicate effectively with both internal and external stakeholders. * Fluent in English, with proficiency in Japanese considered a plus. <p>Job Offer</p> <ul style="list-style-type: none"> * * Competitive salary ranging from 9 to 15 million (total). * Opportunity for international travel (50% domestic), excluding Okinawa and Hokkaido. * Reporting directly to a non-Japanese Managing Director based in the US. * First position in Japan, offering autonomy and leadership in a standalone role. * Chance to influence the direction of cutting-edge technologies and shape the future of semiconductor packaging. <p>To apply online please click the 'Apply' button below. For a confidential discussion about this role please contact Maika Sameda on +81 3 6832 8682.</p>
Company Info	Our client is a renowned player in the semiconductor industry, driving innovation and pushing boundaries in advanced packaging technologies. With a global presence and a commitment to excellence, they offer a dynamic environment where talented professionals can thrive and make a significant impact.
Working Hours	詳しくはお問い合わせください
	Possesses 5+ years of hands-on experience in semiconductor tool engineering,

Qualifications	preferably in back-end packaging or front-end fab processes. Demonstrates strong technical knowledge and problem-solving skills, with the ability to communicate effectively with both internal and external stakeholders. Fluent in English, with proficiency in Japanese considered a plus.
English Level	Fluent (TOEIC 865-)
Japanese Level	Native Level
Salary	JPY - Japanese Yen JPY 9000K - JPY 15000K

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